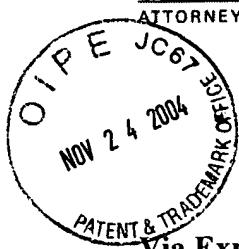


11-26-04

ffw



**ANDREWS**  
ATTORNEYS  
**KURTH LLP**

Via Express Mail  
No. EV434215837US

Andrews & Kurth L.L.P.  
111 Congress Avenue, Suite 1700  
Austin, Texas 78701  
512.320.9200 Phone  
512.320.9292 Fax  
andrewskurth.com

J. Scott Denko  
512.320.9259 Direct  
scottdenko@aklp.com

November 23, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Re: Application No.: 10/620,157  
Filing Date: July 14, 2003  
Title: Thin Scale Outline Package Stack  
Inventors: Glen Roeters, et al.  
Docket No. DPAC-067B

Dear Commissioner:

Please find enclosed the following items:

- 1) Copy of Power of Attorney To Prosecute Applications Before the USPTO;
- 2) Statement Under 37 CFR 3.73(b); and
- 3) a return postcard for confirmation of receipt.

The Commissioner is hereby authorized to charge any fees deemed to be due or credit any overpayment to Deposit Account No. 50-0897, upon which the undersigned is authorized to sign.

Please return the postcard confirming your receipt of the enclosed materials.

Very truly yours,

A handwritten signature of J. Scott Denko.

J. Scott Denko

Enclosures



Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

**REVOCATION OF POWER OF  
ATTORNEY WITH  
NEW POWER OF ATTORNEY  
AND  
CHANGE OF CORRESPONDENCE ADDRESS**

Application Number	10/620,157
Filing Date	7-14-03
First Named Inventor	Glen E. Roeters
Art Unit	
Examiner Name	
Attorney Docket Number	D PAC - 067B

**I hereby revoke all previous powers of attorney given in the above-identified application.**

A Power of Attorney is submitted herewith.

**OR**

I hereby appoint the practitioners associated with the Customer Number:

36,485

Please change the correspondence address for the above-identified application to:

The address associated with  
Customer Number:

36,485

**OR**

Firm or  
Individual Name

Address

City

State

Zip

Country

Telephone

Fax

I am the:

Applicant/Inventor.

Assignee of record of the entire interest. See 37 CFR 3.71.  
Statement under 37 CFR 3.73(b) is enclosed. (Form PTO/SB/96)

**SIGNATURE of Applicant or Assignee of Record**

Signature

Name

Stephanie Lucie

Date

11/18/04

Telephone

512-454-9531

NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below.

\*Total of \_\_\_\_\_ forms are submitted.

This collection of information is required by 37 CFR 1.36. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 3 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

**STATEMENT UNDER 37 CFR 3.73(b)**Applicant/Patent Owner: Staktek Group L.P. (Inventor: Glen Roeters, et al.)Application No./Patent No.: 10/620,157 Filed/Issue Date: July 14, 2003Entitled: Thin Scale Outline Package Stack

Staktek Group L.P., a limited partnership  
(Name of Assignee) (Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

1.  the assignee of the entire right, title, and interest; or
2.  an assignee of less than the entire right, title and interest.  
The extent (by percentage) of its ownership interest is \_\_\_\_\_ %

in the patent application/patent identified above by virtue of either:

A.  An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel \_\_\_\_\_, Frame \_\_\_\_\_, or for which a copy thereof is attached.

**OR**

B.  A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

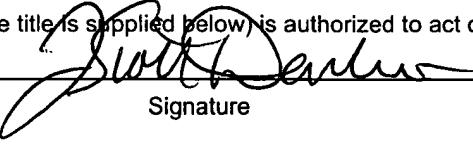
1. From: Glen Roeters, et al. To: DPAC Technologies Corp.  
The document was recorded in the United States Patent and Trademark Office at  
Reel 014305, Frame 0221, or for which a copy thereof is attached.
2. From: DPAC Technologies Corp. To: Staktek Group L.P.  
The document was recorded in the United States Patent and Trademark Office at  
Reel \_\_\_\_\_, Frame \_\_\_\_\_, or for which a copy thereof is attached.
3. From: \_\_\_\_\_ To: \_\_\_\_\_  
The document was recorded in the United States Patent and Trademark Office at  
Reel \_\_\_\_\_, Frame \_\_\_\_\_, or for which a copy thereof is attached.

Additional documents in the chain of title are listed on a supplemental sheet.

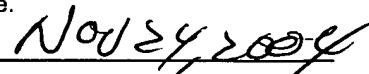
Copies of assignments or other documents in the chain of title are attached.

[NOTE: A separate copy (i.e., a true copy of the original assignment document(s)) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.08]

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

J. Scott Denko

Signature



Date

Printed or Typed Name512-320-9200

Telephone Number

Attorney of Record, Reg. No. 37,606Title

This collection of information is required by 37 CFR 3.73(b). The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND  
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

O I P E JC67  
NOV 24 2004  
PATENT & TRADEMARK OFFICE  
FEBRUARY 05, 2004

PTAS

STETINA BRUNDA GARRED & BRUCKER  
KIT M. STETINA  
75 ENTERPRISE  
SUITE 250  
ALISO VIEJO, CA 92656



\*102508650A\*

UNITED STATES PATENT AND TRADEMARK OFFICE  
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF  
THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS  
AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER  
REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE  
INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA  
PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD  
FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY  
CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723.  
PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE,  
ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY,  
SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 07/14/2003

REEL/FRAME: 014305/0221

NUMBER OF PAGES: 4

BRIEF: ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:

ROETERS, GLEN

DOC DATE: 07/01/2003

ASSIGNOR:

SPRINT, JOHN PATRICK

DOC DATE: 07/01/2003

ASSIGNOR:

MEARING, JOEL ANDREW

DOC DATE: 07/01/2003

ASSIGNEE:

DPAC TECHNOLOGIES CORP.  
7321 LINCOLN WAY  
GARDEN GROVE, CALIFORNIA 92841

SERIAL NUMBER: 10620157

FILING DATE: 07/14/2003

PATENT NUMBER:

ISSUE DATE:

014305/0221 PAGE 2

DIANE RUSSELE, PARALEGAL  
ASSIGNMENT DIVISION  
OFFICE OF PUBLIC RECORDS

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NOV 24 2004  
RE  
PATENT & TRADEMARK OFFICE

Form PTO-1595  
(Rev. 03/01)  
OMB No. 0651-0027 (exp. 5/11/2002)

Tab settings

07-28-2003



102508650

U. S. DEPARTMENT OF COMMERCE  
U. S. Patent and Trademark Office

17410 U.S. PTO  
17410 U.S. PTO  
07/14/03

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Glen Roeters  
John Patrick Sprint  
Joel Andrew Mearing

7/14/03

2. Name and address of receiving party(ies)

Name: DPAC TECHNOLOGIES CORP

Internal Address: \_\_\_\_\_

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_

Execution Date 07/01/2003

Street Address: 7321 Lincoln Way

City: Garden Grove State: CA Zip: 92841

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is 07/01/2003

A. Patent Application No.(s)

10620157

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kit M. Stetina

Internal Address: \_\_\_\_\_

STETINA BRUNDA GARRED & BRUCKER

Street Address: 75 Enterprise-Suite 250

City: Aliso Viejo State: CA Zip: 92656

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

19-4330

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Kit M. Stetina

Name of Person Signing

Signature

7/14/03  
Date

Total number of pages including cover sheet, attachments, and documents

4

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

**COPY**

ASSIGNMENT OF APPLICATION		Docket Number DENSE-067B
<p>Whereas, We, <u>Glen Roeters</u> of <u>Huntington Beach, California</u>, <u>John Patrick Sprint</u> of <u>Huntington Beach, California</u> and <u>Joel Andrew Mearig</u> of <u>Huntington Beach, California</u>, hereafter referred to as applicant, have invented certain new and useful improvements in <u>THIN SCALE OUTLINE PACKAGE STACK</u>.</p> <p><input type="checkbox"/> for which an application for a United States Patent was filed on _____, Application Number _____ / _____.</p> <p><input checked="" type="checkbox"/> X for which an application for a United States Patent was executed on _____, and</p> <p>Whereas, <u>DPAC TECHNOLOGIES CORP</u> of <u>Garden Grove, California</u> herein referred to "assignee" whose mailing address is <u>7321 Lincoln Way, Garden Grove, California, 92841</u> is desirous of acquiring the entire right, title and interest in the same;</p> <p>Now, therefore, in consideration of the sum of One dollars (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said improvement in the United States, and by these presents do hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, Assignor's entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals, continuations, and continuations-in-part thereof, and all United States Letters patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, including the full right to claim for any such application the priority benefits of the International Convention for the Protection of Industrial Property and other priority-conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, divisions, continuations, continuations-in-part, renewals and reissues thereof; and Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument; I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof; and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.</p> <p>Executed this <u>1<sup>st</sup></u> day of <u>July</u>, 20____.</p> <p>at <u>DPAC Technologies, Garden Grove, CA</u></p> <p><u>Joel Andrew Mearig</u></p> <p>Joel Andrew Mearig</p> <p>State of <u>CA</u> ) SS.</p> <p>County of <u>Orange</u></p> <p>Before me personally appeared said Joel Andrew Mearig</p> <p>and acknowledged the foregoing instrument to be his free act and deed this <u>1<sup>st</sup></u></p> <p>day of <u>July</u>, 2003.</p> <p><u>Robertta Y. Huff</u> (Notary Public)</p> <p>Note: Digital images of the inventors and signers of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required. <u>Some offices require a copy of the original signature. Sep 25, 2004</u></p> <p>x Total of <u>2</u> forms are submitted</p> <p>page 3 of 3</p>		

**COPY**

## ASSIGNMENT OF APPLICATION

Docket Number DENSE-067B

Whereas, We, Glen Roeters of Huntington Beach, California, John Patrick Sprint of Huntington Beach, California and Joel Andrew Mearig of Huntington Beach, California, hereafter referred to as applicant, have invented certain new and useful improvements in THIN SCALE OUTLINE PACKAGE STACK.

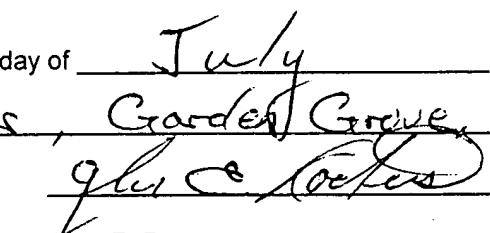
for which an application for a United States Patent was filed on \_\_\_\_\_,  
 Application Number \_\_\_\_\_ / \_\_\_\_\_  
 X for which an application for a United States Patent was executed on \_\_\_\_\_, and

Whereas, DPAC TECHNOLOGIES CORP of Garden Grove, California herein referred to "assignee" whose mailing address is 7321 Lincoln Way, Garden Grove, California, 92841 is desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of One dollars (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said improvement in the United States, and by these presents do hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, Assignor's entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals, continuations, and continuations-in-part thereof, and all United States Letters patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, including the full right to claim for any such application the priority benefits of the International Convention for the Protection of Industrial Property and other priority-conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, divisions, continuations, continuations-in-part, renewals and reissues thereof; and Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument; I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof; and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this 15<sup>th</sup> day of July, 2003.

at DPAC Technologies, Garden Grove, CA.



Glen E. Roeters

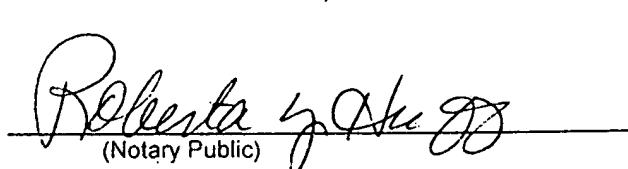
State of CA ) SS.

County of Orange

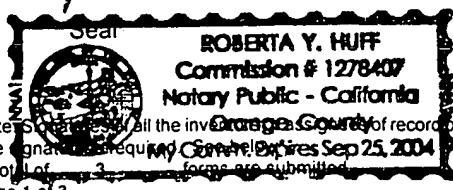
Before me personally appeared said Glen E. Roeters

and acknowledged the foregoing instrument to be his free act and deed this

day of July, 2003.



(Notary Public)



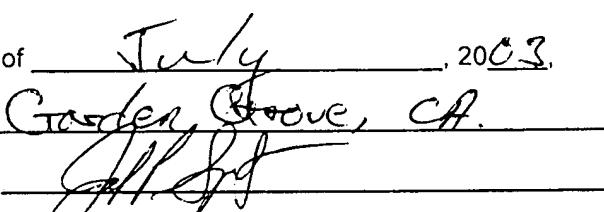
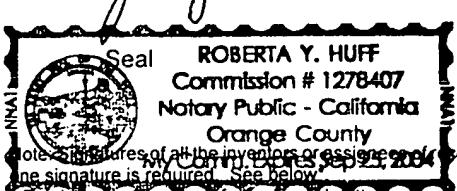
Note: Signatures of all the inventors or assignees or record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required.

My Commission Expires Sep 25, 2004

x Total of 3 forms are submitted.

Page 1 of 3

**COPY**

ASSIGNMENT OF APPLICATION		Docket Number DENSE-067B
<p>Whereas, We, <u>Glen Roeters</u> of <u>Huntington Beach, California</u>, <u>John Patrick Sprint</u> of <u>Huntington Beach, California</u> and <u>Joel Andrew Mearig</u> of <u>Huntington Beach, California</u>, hereafter referred to as applicant, have invented certain new and useful improvements in <u>THIN SCALE OUTLINE PACKAGE STACK</u>.</p> <p><input type="checkbox"/> for which an application for a United States Patent was filed on _____, Application Number _____ / _____.</p> <p><input checked="" type="checkbox"/> X for which an application for a United States Patent was executed on _____, and</p> <p>Whereas, <u>DPAC TECHNOLOGIES CORP</u> of <u>Garden Grove, California</u> herein referred to "assignee" whose mailing address is <u>7321 Lincoln Way, Garden Grove, California, 92841</u> is desirous of acquiring the entire right, title and interest in the same;</p> <p>Now, therefore, in consideration of the sum of One dollars (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said improvement in the United States, and by these presents do hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, Assignor's entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals, continuations, and continuations-in-part thereof, and all United States Letters patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, including the full right to claim for any such application the priority benefits of the International Convention for the Protection of Industrial Property and other priority-conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, divisions, continuations, continuations-in-part, renewals and reissues thereof; and Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument; I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof; and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.</p> <p>Executed this <u>1st</u> day of <u>July</u>, 20<u>03</u>, at <u>DPAC Technologies, Garden Grove, CA.</u></p> <p> John Patrick Sprint</p> <p>State of <u>CA</u> ) SS. County of <u>Orange</u></p> <p>Before me personally appeared said John Patrick Sprint and acknowledged the foregoing instrument to be his free act and deed this <u>1st</u> day of <u>July</u>, 20<u>03</u>.</p> <p> Seal ROBERTA Y. HUFF Commission # 1278407 Notary Public - California Orange County Note: Signatures of all the inventors or assignees and a record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required. See below. x Total of <u>3</u> forms are submitted.</p>		

## ASSIGNMENT OF APPLICATION

Docket Number DENSE-067B

Whereas, We, Glen Roeters of Huntington Beach, California, John Patrick Sprint of Huntington Beach, California and Joel Andrew Mearig of Huntington Beach, California, hereafter referred to as applicant, have invented certain new and useful improvements in THIN SCALE OUTLINE PACKAGE STACK.

for which an application for a United States Patent was filed on \_\_\_\_\_  
Application Number \_\_\_\_\_ / \_\_\_\_\_  
 X for which an application for a United States Patent was executed on \_\_\_\_\_, and

Whereas, DPAC TECHNOLOGIES CORP of Garden Grove, California herein referred to "assignee" whose mailing address is 7321 Lincoln Way, Garden Grove, California, 92841 is desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of One dollars (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said improvement in the United States, and by these presents do hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, Assignor's entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals, continuations, and continuations-in-part thereof, and all United States Letters patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, including the full right to claim for any such application the priority benefits of the International Convention for the Protection of Industrial Property and other priority-conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, divisions, continuations, continuations-in-part, renewals and reissues thereof; and Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument; I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof; and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this 1<sup>st</sup> day of July, 20\_\_\_\_.

at DPAC Technologies, Garden Grove, CA



Joel Andrew Mearig

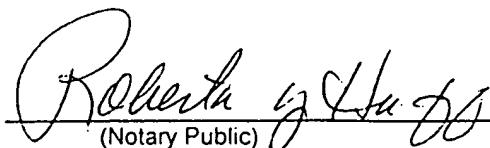
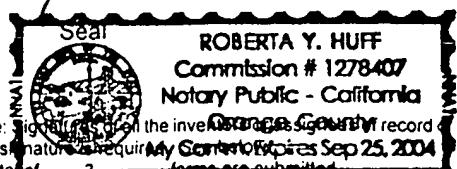
State of CA ) SS.

County of Orange)

Before me personally appeared said Joel Andrew Mearig

and acknowledged the foregoing instrument to be his free act and deed this 1<sup>st</sup>

day of July, 2003.



(Notary Public)

Note: Signatures of all inventors and signatory record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required. My Seal is valid Sep 25, 2004  
x Total of 2 pages submitted  
page 3 of 3

## **ASSIGNMENT OF APPLICATION**

Docket Number DENSE-067B

Whereas, We, Glen Roeters of Huntington Beach, California, John Patrick Sprint of Huntington Beach, California and Joel Andrew Mearig of Huntington Beach, California, hereafter referred to as applicant, have invented certain new and useful improvements in THIN SCALE OUTLINE PACKAGE STACK.

for which an application for a United States Patent was filed on \_\_\_\_\_,  
Application Number \_\_\_\_\_ / \_\_\_\_\_.  
 for which an application for a United States Patent was executed on \_\_\_\_\_, and

Whereas, DPAC TECHNOLOGIES CORP of Garden Grove, California herein referred to "assignee" whose mailing address is 7321 Lincoln Way, Garden Grove, California, 92841 is desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of One dollars (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said improvement in the United States, and by these presents do hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, Assignor's entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals, continuations, and continuations-in-part thereof, and all United States Letters patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, including the full right to claim for any such application the priority benefits of the International Convention for the Protection of Industrial Property and other priority-conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, divisions, continuations, continuations-in-part, renewals and reissues thereof; and Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument; I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof, and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this 15<sup>th</sup> day of July, 2003.

at DPAC Technologies, Garden Grove, CA.

~~Glen F Roeters~~

State of CA 1 SS.

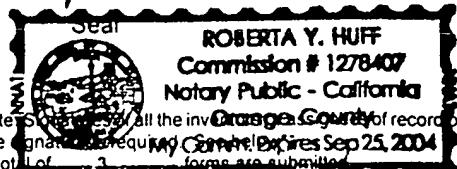
County of Orange

Before me personally appeared said Glen E. Roeters

and acknowledged the foregoing instrument to be his free act and deed this

day of July, 2003

Robert J. Akers  
(Notary Public)



Note: Signatures for all the involved parties of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required. **Copy Date: Sep 25, 2004**  
 Total of 3 forms are submitted.

## ASSIGNMENT OF APPLICATION

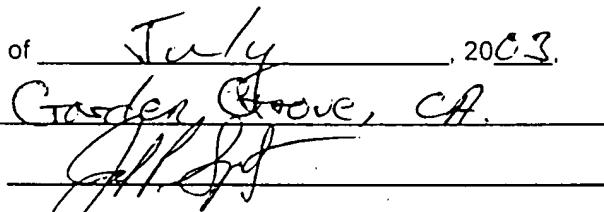
Docket Number DENSE-0678

Whereas, We, Glen Roeters of Huntington Beach, California, John Patrick Sprint of Huntington Beach, California and Joel Andrew Mearig of Huntington Beach, California, hereafter referred to as applicant, have invented certain new and useful improvements in THIN SCALE OUTLINE PACKAGE STACK.

for which an application for a United States Patent was filed on \_\_\_\_\_  
Application Number \_\_\_\_\_ /  
 for which an application for a United States Patent was executed on \_\_\_\_\_, and

Whereas, DPAC TECHNOLOGIES CORP of Garden Grove, California herein referred to "assignee" whose mailing address is 7321 Lincoln Way, Garden Grove, California, 92841 is desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of One dollars (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said improvement in the United States, and by these presents do hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, Assignor's entire right, title and interest in, to and under said improvements, and said application and all divisions, renewals, continuations, and continuations-in-part thereof, and all United States Letters patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, including the full right to claim for any such application the priority benefits of the International Convention for the Protection of Industrial Property and other priority-conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, divisions, continuations, continuations-in-part, renewals and reissues thereof; and Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument; I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof; and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

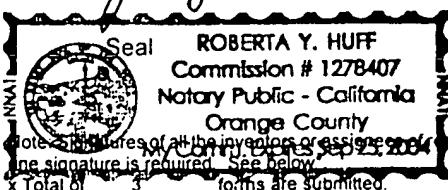
Executed this 1st day of July, 2003,  
at DPAC Technologies, Garden Grove, CA.  
  
John Patrick Sprint

State of CA) SS.

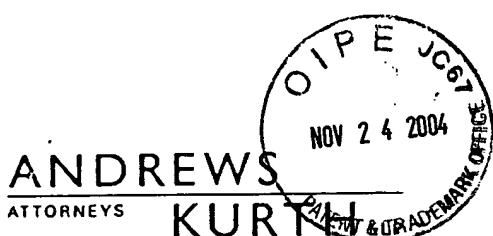
County of Orange)

Before me personally appeared said John Patrick Sprint

and acknowledged the foregoing instrument to be his free act and deed this 1st  
day of July, 2003.



Page 2 of 3



Andrews & Kurth L.L.P.  
111 Congress Avenue, Suite 1700  
Austin, Texas 78701  
512.320.9200 Phone  
512.320.9292 Fax  
andrewskurth.com

J. Scott Denko  
512.320.9259 Direct  
scottdenko@aklp.com

Via Express Mail  
No. EV434216262US

June 25, 2004

Box Fee – Assignment Division  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Re: Application No.: 10/620,157  
Filing Date: 7/14/2003  
Title: THIN SCALE OUTLINE PACKAGE STACK  
Inventors: Glen E. Roeters, John P. Sprint, Joel A. Mearig  
Docket No. DPAC-067B

Dear Commissioner:

Please find enclosed the following items:

- 1) Assignment, together with Assignment Recordation Form (with duplicate copy);
- 2) Fee Form 2004 (with duplicate copy); and
- 3) a return postcard for confirmation of receipt.

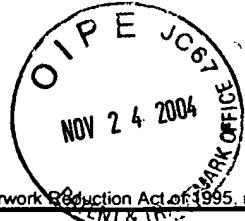
The Commissioner is hereby authorized to charge any fees deemed to be due or credit any overpayment to Deposit Account No. 50-0897, upon which the undersigned is authorized to sign.

Please return the postcard confirming your receipt of the enclosed materials.

Very truly yours,



J. Scott Denko



Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

# FEE TRANSMITTAL for FY 2004

Effective 10/01/2003. Patent fees are subject to annual revision.

 Applicant claims small entity status. See 37 CFR 1.27

TOTAL AMOUNT OF PAYMENT	(\$ 40.00)
-------------------------	------------

Complete if Known	
Application Number	10/620,157
Filing Date	7/14/2003
First Named Inventor	Glen E. Roeters
Examiner Name	Unknown
Art Unit	Unknown
Attorney Docket No.	DPAC-067B

## METHOD OF PAYMENT (check all that apply)

 Check  Credit card  Money Order  Other  None

 Deposit Account:

 Deposit Account Number  
 Deposit Account Name

50-0897

Andrews Kurth LLP

The Director is authorized to: (check all that apply)

Charge fee(s) indicated below  Credit any overpayments  
 Charge any additional fee(s) or any underpayment of fee(s)  
 Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.

## FEE CALCULATION

## 1. BASIC FILING FEE

Large Entity	Small Entity	Fee Code (\$)	Fee Code (\$)	Fee Description	Fee Paid
1001	770	2001	385	Utility filing fee	
1002	340	2002	170	Design filing fee	
1003	530	2003	265	Plant filing fee	
1004	770	2004	385	Reissue filing fee	
1005	160	2005	80	Provisional filing fee	
SUBTOTAL (1) (\$)					

## 2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE

Total Claims	Independent Claims	Multiple Dependent	Extra Claims	Fee from below	Fee Paid
			-20** =	X	=
			- 3*** =	X	=

Large Entity	Small Entity	Fee Description
1202	18	2202 9 Claims in excess of 20
1201	86	2201 43 Independent claims in excess of 3
1203	290	2203 145 Multiple dependent claim, if not paid
1204	86	2204 43 ** Reissue independent claims over original patent
1205	18	2205 9 ** Reissue claims in excess of 20 and over original patent
SUBTOTAL (2) (\$)		

\*\*or number previously paid, if greater; For Reissues, see above

## FEE CALCULATION (continued)

## 3. ADDITIONAL FEES

Large Entity Small Entity

Fee Code (\$)	Fee Code (\$)	Fee Description	Fee Paid
1051	130	2051 65 Surcharge - late filing fee or oath	
1052	50	2052 25 Surcharge - late provisional filing fee or cover sheet	
1053	130	1053 130 Non-English specification	
1812	2,520	1812 2,520 For filing a request for ex parte reexamination	
1804	920*	1804 920* Requesting publication of SIR prior to Examiner action	
1805	1,840*	1805 1,840* Requesting publication of SIR after Examiner action	
1251	110	2251 55 Extension for reply within first month	
1252	420	2252 210 Extension for reply within second month	
1253	950	2253 475 Extension for reply within third month	
1254	1,480	2254 740 Extension for reply within fourth month	
1255	2,010	2255 1,005 Extension for reply within fifth month	
1401	330	2401 165 Notice of Appeal	
1402	330	2402 165 Filing a brief in support of an appeal	
1403	290	2403 145 Request for oral hearing	
1451	1,510	1451 1,510 Petition to institute a public use proceeding	
1452	110	2452 55 Petition to revive - unavoidable	
1453	1,330	2453 665 Petition to revive - unintentional	
1501	1,330	2501 665 Utility issue fee (or reissue)	
1502	480	2502 240 Design issue fee	
1503	640	2503 320 Plant issue fee	
1460	130	1460 130 Petitions to the Commissioner	
1807	50	1807 50 Processing fee under 37 CFR 1.17(q)	
1806	180	1806 180 Submission of Information Disclosure Stmt	
8021	40	8021 40 Recording each patent assignment per property (times number of properties)	40.00
1809	770	2809 385 Filing a submission after final rejection (37 CFR 1.129(a))	
1810	770	2810 385 For each additional invention to be examined (37 CFR 1.129(b))	
1801	770	2801 385 Request for Continued Examination (RCE)	
1802	900	1802 900 Request for expedited examination of a design application	
Other fee (specify)			

\*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$ 40.00)

(Complete if applicable)			
Name (Print/Type)	J. Scott Denko	Registration No. (Attorney/Agent)	37,606
Signature		Date	06/25/04

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

This collection of information is required by 37 CFR 1.17 and 1.27. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



Attorney Docket No.: DPAC-067B

Form PTO-1619A  
Expires 06/30/99  
OMB 0651-0027

U.S. Department of Commerce  
Patent and Trademark Office

**RECORDATION FORM COVER SHEET  
PATENTS ONLY**

TO: THE HONORABLE COMMISSIONER OF PATENTS AND TRADEMARKS: *Please record the attached original document(s) or copy(ies).*

**SUBMISSION TYPE**

New  
 Resubmission (non-recordations)  
Document ID # \_\_\_\_\_  
 Correction of PTO Error  
Reel # \_\_\_\_\_ Frame # \_\_\_\_\_  
 Corrective Document  
Reel # \_\_\_\_\_ Frame # \_\_\_\_\_

**CONVEYANCE TYPE**

Assignment  
 Change of Name  
 Security Agreement  
 Merger  
Other: \_\_\_\_\_  
\_\_\_\_\_

**CONVEYING PARTY(IES)**

Name (line 1): DPAC Technologies Corp.  
Name (line 2): (formerly known as Dense-Pac  
Name (line 3): Microsystems, Inc.)  
Name (line 4):  
Name (line 5):  
Name (line 6):  
Name (line 7):  
Execution Date: June 9, 2004  
 Mark if additional names of conveying parties attached.

**RECEIVING PARTY(IES):**

Name: Staktek Group L.P.  
Address: 8900 Shoal Creek Blvd., Suite 125  
City: Austin  
State: TX Zip: 78757

If document to be recorded is an assignment and the receiving party is not domiciled in the United States, an appointment of a domestic representative is attached. *(Designation must be a separate document from Assignment.)*

**PAGES** Enter the total number of pages of the attached conveyance document, including any attachments. 10

**APPLICATION NUMBER(S) OR PATENT NUMBER(S)**  Mark if additional numbers attached.  
*Enter either the Patent application number or the patent number (DO NOT ENTER BOTH numbers for the same property)*

Patent Application No(s).:  
10/620,157  
\_\_\_\_\_  
\_\_\_\_\_

Patent No(s).:  
\_\_\_\_\_  
\_\_\_\_\_

If this document is being filed together with a new patent application, enter the date the application was signed by the first named executing inventor:

**CORRESPONDENT NAME AND ADDRESS**

Name: J. Scott Denko  
Internal address: Andrews & Kurth LLP  
111 Congress Avenue, Suite 1700  
  
Street address: Same  
  
City: Austin  
State: Texas Zip: 78701

**PATENT COOPERATION TREATY (PCT)**

Enter PCT application number  
only if a U.S. application number  
has not been assigned.

PCT \_\_\_\_\_

**NUMBER OF PROPERTIES**

Enter the total number of properties involved: One (1)

**FEE AMOUNT**

For Amount for Properties Listed (37 CFR 3.41):

\$40.00

Method of Payment:

Enclosed (included in the check covering the filing fee), or

Deposit Account

(Enter for payment by deposit account or if additional fees can be charged to the account.)

Debit Account No.: 50-0897

Authorized to charge additional fees or credit any overpayment to Deposit Account No. 50-0897.

**STATEMENT AND SIGNATURE**

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Charges to deposit account are authorized, as indicated herein.

J. Scott Denko

Name of Person Signing



June 25, 2004

Date

06/08/04

**EXHIBIT A**  
**ASSIGNMENT OF DPAC ASSETS**

WHEREAS, DPAC Technologies Corp. (formerly known as Dense-Pac Microsystems, Inc.) ("DPAC") owns certain intellectual properties consisting of inventions, patents, and patent applications (enumerated on attached and incorporated Exhibit 1) (the "DPAC Assets");

WHEREAS, Staktek Group L.P., a Texas limited partnership, desires to acquire and DPAC desires to assign to Staktek Group L.P., all of DPAC's rights in the DPAC Assets;

NOW, THEREFORE, DPAC, for itself and its predecessors in interest for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby ASSIGN to Staktek Group L.P., all right, title and interest in the DPAC Assets, this assignment including, but not being limited to:

1. The ASSIGNED INVENTIONS enumerated on Exhibit 1 whether created by DPAC, its predecessors, its legal representatives or its assigns in the United States or any other country or place anywhere in the world;
2. The ASSIGNED PATENTS enumerated on Exhibit 1;
3. The ASSIGNED PATENT APPLICATIONS enumerated on Exhibit 1;
4. All rights of action on account of past, present, and future unauthorized use or infringement of said DPAC Assets including, but not limited to all rights to damages so accrued;
5. The right, where allowed by law, to file in the name of Staktek Group L.P. applications for patent and like protection for any one or more of the DPAC Assets in any country or countries foreign to the United States;
6. All international and domestic rights or priorities associated with any one of the DPAC Assets; and

This Assignment shall be binding upon and shall inure to the benefit of the successors, assigns, and legal representatives of the parties.

**BEST AVAILABLE COPY**

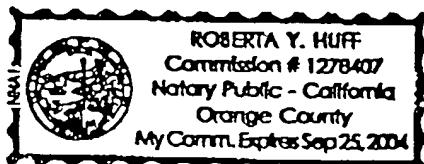
06/08/04

EXECUTED on the EFFECTIVE DATE indicated below:

Assignor: DPAC TECHNOLOGIES CORP.

Date: JUNE 9, 2004By: Creighton K. Earley  
[DPAC TECHNOLOGIES CORP OFFICER]Name: Creighton K. EarleyTitle: CHIEF EXECUTIVE OFFICERTHE STATE OF [Calif]  
COUNTY OF [Orange]§  
§  
§This instrument was acknowledged by DPAC Officer on this the 9 day ofJune, 2004.

(Seal)

Roberta Y. Huff  
Notary Public in and for the State of [ ]My commission expires: 9/25/04**BEST AVAILABLE COPY**

## EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required	Action Assigned
DENSE-002A	Universal Package and Method of Forming the Same	Patent	Original	4/23/1999	09/238,664	4/24/2001	6,222,737	Universal Package and Method of Forming the Same	Issued. 3 1/2 year maintenance fees due 10/24/04.	N/A	N/A	None
DENSE-002G	Universal Package and Method of Forming the Same	Patent	Divisional	9/19/2000	09/664,938	3/26/2002	6,360,433	Universal Package and Method of Forming the Same	Issued. 3 1/2 year maintenance fees due 09/26/05.	N/A	N/A	None
DENSE-003A	Stackable Chip Package with Flex Carrier	Patent	Original	1/13/2000	09/482,294	7/21/2001	6,262,895	Stackable Chip Package with Flex Carrier	Issued. 3 1/2 year maintenance fees due 01/17/05.	N/A	N/A	None
DENSE-003C	Stackable Chip Package with Flex Carrier	Patent	Continuation	4/10/2001	09/838,773	10/29/2002	6,473,308	Stackable Chip Package with Flex Carrier	Issued. 3 1/2 year maintenance fees due 04/29/2006.	N/A	N/A	None
DENSE-005A	CSP Stacking Technology Using Rigid/Flex Construction	Patent	Original	3/24/2000	09/535,641	8/20/2002	6,437,433 B1	CSP Stacking Technology Using Rigid/Flex Construction	Issued. 3 1/2 year maintenance fees due 02/20/2006.	PTO	None	None
DENSE-012A	Mechanically Registered and Interconnected Chip Stack	Patent	Original	6/15/2000	09/594,989			Mechanically Registered and Attachable Chip Stack	Closed.	N/A	N/A	None
DENSE-012G	Mechanically Registered and Attachable Chip Stack	Patent	Divisional	7/24/2002	10/202,185			Mechanically Registered and Attachable Chip Stack	Issued. 3 1/2 year maintenance fee due 12/09/2006	PTO	None	None
DENSE-013A	Chip Stack and Method of Making Same	Patent	Original	4/13/1995	08/421,801	3/18/1997	5,612,570	Chip Stack and Method of Making Same	Issued. 7 1/2 year maintenance fee due 09/18/2004.	N/A	N/A	None
ISE-011PC	Chip Stack and Method of Making Same	Patent	PCT					Chip Stack and Method of Making Same	Closed.	N/A	N/A	None
DENSE-013A	Modular Panel Stacking Process	Patent	Original	11/17/1997	08/971,499	02/09/1999	5,869,353	Modular Panel Stacking Process	Issued. 7 1/2 year maintenance fee due 08/09/2007.	N/A	N/A	None
DENSE-013X	Reissue: Modular Panel Stacking Process	Other	Re-issue	8/3/2000	09/633,297			Modular Panel Stacking Process	Awaiting Reply re: Non-Recordation of Document	PTO	None	
DENSE-016A	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Original		07/851,755			IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Closed.	N/A	N/A	None

## EXHIBIT 1 - DPAC Assets

EXHIBIT 1 - DPAC Assets									
Case	TradeMark - Invention	Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent Trademark Registration Number	Description	Status
DENSE-016EP	IC Chip Package and Method of Making the Same	Patent	European		93308306.9			IC Chip Package and Method of Making the Same	Closed.
DENSE-016JP	IC Chip Package and Method of Making the Same	Patent	Japan		5-516611			IC Chip Package and Method of Making the Same	Closed.
DENSE-016PC	IC Chip Package and Method of Making the Same	Patent	PCT	3/10/1993	PCT/US93/02202	5/17/1994	5,311,096	IC Chip Package and Method of Making the Same	Closed.
DENSE-016G	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlaying Substrate	Patent	Divisional	7/29/1992	07/9202763	5/17/1994	5,311,096	IC Chip Package having Chip Attached to and Wire Bonded within an Overlaying Substrate	Issued. 1 1/2 year maintenance fee due 1/17/2005.
DENSE-017A	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Original	5/5/1999	09/305,534	11/27/2001	6,323,060 B1	Stackable Flex Circuit IC Package and Method of Making Same	Issued. 3 1/2 year maintenance fee due 05/27/2005.
DENSE-017EP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	European	10/26/2001	932113.6			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.
DENSE-017HK	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Hong Kong	9/25/2002	1045759			Stackable Flex Circuit IC Package and Method of Making Same	** Closed.
DENSE-017JP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Japan	10/29/2001	2000-616064			Stackable Flex Circuit IC Package and Method of Making the Same	** Closed.
ISE-017KS	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Korea	11/3/2001	2001-7014056			Stackable Flex Circuit IC Package and Method of Making the Same	** Closed.
DENSE-017PC	Stackable Flex Circuit IC Package and Method of Making Same	Patent	PCT	5/5/2000	PCT/US00/12393			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.
DENSE-017B	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation-in-Part	5/19/2000	09/574,321	2/26/2002	6,351,029 B1	Flex Wrap Carrier and Method	Issued. 3 1/2 year maintenance fees due 08/26/2005.
DENSE-017BPC	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	PCT	3/29/2001	PCT/US01/0064			Stackable Flex Circuit Chip Package and Method of Making Same	Closed.

A U S : 337564.4

Page 2 of 8 - Exhibit 1

DPAC  
STAKTER

## EXHIBIT 1 - DPAC Assets

Case	Title/Mark - Invention	Item # Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required	Action Assigned
DENSE-017BT	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Taiwan	4/24/2001	90109731			Stackable Flex Circuit Package and Method of Making Same	Closed.	PTO	None	None
DENSE-017B1	Flex Wrap Carrier and Method	Patent	Continuation-in-Part					Flex Wrap Carrier and Method	Closed, pursuant to client instructions.	N/A	N/A	None
DENSE-017BG	Stackable Flex Circuit Package and Method of Making Same	Patent	Divisional	6/25/2001	09/888,785	7/10/2002	6426240 B1	Stackable Flex Circuit Package and Method of Making Same	Issued. 3 1/2 year maintenance fees due 01/30/2006.	N/A	N/A	None
DENSE-017C	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation	6/25/2001	09/888,792	2/4/2003	6,514,793	Stackable Flex Circuit Chip Package and Method of Making Same	Issued. 3 1/2 year maintenance fees due 08/04/2006.	N/A	N/A	None
DENSE-017G	Stackable Flex Circuit and Method of Making Same	Patent	Divisional	1/13/2000	09/706,015	7/30/2002	6,426,549 B1	Stackable Flex Circuit and Method of Making Same	Issued. 3 1/2 year maintenance fees due 01/30/2006.	N/A	N/A	None
DENSE-018A	Chip Stack and Method of Making Same	Patent	Original	5/5/1998	09/073,254	1/30/2001	6,180,881 B1	Chip Stack and Method of Making Same	Issued. 3 1/2 year maintenance fees due 07/30/2004.	N/A	N/A	None
DENSE-018EP	Chip Stack and Method of Making Same	Patent	European	11/14/2000	99920334.2			Chip Stack and Method of Making Same		N/A	N/A	None
DENSE-018JP	Chip Stack and Method of Making Same	Patent	Japan	10/31/2000	2000-547656			Chip Stack and Method of Making Same	** Closed.	PTO	None	None
'SE-018KS	Chip Stack and Method of Making Same	Patent	Korea	11/6/2000	2000-7012284			Chip Stack and Method of Making Same	Closed.	DPAC	5/4/2004	
DENSE-018PC	Chip Stack and Method of Making Same	Patent	PCT			PCT/US01/09744		Chip Stack and Method of Making Same	Closed.	N/A	None	
DENSE-019A	Module and Method of Making Same	Patent	Original					Module and Method of Making Same	Unified - Closed.	N/A	N/A	
DENSE-020A	Clip Stack Having Interconnected Bonding Pads on Sagged Edges of Chips	Patent	Original		08/083,092			Clip Stack Having Interconnected Bonding Pads on Sagged Edges of Chips	Closed.	N/A	N/A	

AUS3575644

Page 3 of 8 - Exhibit 1

DPAC

STAKTEK

*EE*

## EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

JUN 10 '04 14:53

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Action Assigned
DENSE-021A	IC Chip Stack and Method of Making	Patent	Original	08/119,518				IC Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-022A	Memory Module Having Memory Package	Patent	Original	08/083,068				Memory Module Having Memory Package Stages	Closed.	N/A	None
DENSE-023A	Chip Stack and Method of Making Same	Patent	Original	08/935,276				Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023G	Chip Stack and Method of Making Same	Patent	Divisional	08/097,449				Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-025A	Externally Configurable Chip Carrier	Patent	Original	07/552,578				Externally Configurable Chip Carrier	Closed.	N/A	None
DENSE-026A	Chip Stack with Active Cooling System	Patent	Original	7/15/2000	09/594,363	5/22/2001	6,236,565 B1	Active Cooling System for Chip Stack	Issued. 3 1/2 year maintenance fees due 1/12/2004.	DPAC	None
DENSE-027A	Chip Stack with Differing Chip Package Types	Patent	Original	7/24/2001	09/912,010	9/30/2003	6,627,984	Frame/Multi-Chip Stacking of Differing Package Types	Issued. 3 1/2 year maintenance fee due 03/30/2007.	DPAC	8/31/2003
DENSE-027G	Chip Stack with Differing Chip Package Types	Patent	Divisional	10/3/2002	10/263,839			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	PTO	None
SE-027PC	Chip Stack with Differing Chip Package Types	Patent	PCT	7/9/2002	PCT/US02/1546			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	DPAC	1/24/2004
DENSE-028A	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Original	6/21/2000	09/598,373	6/11/2002	6,404,043	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fee due 12/11/2005.	N/A	None
DENSE-028B	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part					Panel Stacking of BGA Devices	Closed.	N/A	None
DENSE-028B1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part	10/14/2001	10/017,553	5/20/2003	6,566,746	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fees due 11/20/2006.	N/A	None

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## EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required	Action Assigned
DENSE-028B1G	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	12/11/2002	10/316,566			Panel Stacking of BGA Devices	** Closed.	PTO	None	
DENSE-028C	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	8/6/2001	09/922,977	4/8/2003	6,544,815	Panel Stacking of BGA Devices to Form 3-D Modules	Issued. 3 1/2 year maintenance fees due 10/08/2006.	u/a	None	
DENSE-028GC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation	11/8/2002	10/290,994			Panel Stacking of BGA Devices to Form 3-D Modules	** Closed.	PTO	None	
DENSE-028PC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	PCT	3/29/2001	PCT/US01/0130			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Closed.	N/A	None	
DENSE-028T1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Taiwan	5/14/2001	90110594			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	** Closed.	DPAC	2/28/2004	
DENSE-029A	Flux/Underfill Incorporating Ball Spaces	Patent	Original	6/23/2000	09/602,056			Flux/Underfill Incorporating Ball Spaces	Closed.	N/A	None	
DENSE-030A	Module with One Side Stacked Memory	Patent	Original	1/9/2001	09/757,155			Single Density Board with One Side Stack	Closed	N/A	None	
DENSE-032A	BGA Device with Flex Flap	Patent	Original					BGA Device with Flex Flap	Closed.	DPAC	None	
DENSE-033A	Heterogeneous Enhanced L-P Stack	Patent	Original					Heterogeneous Enhanced L-P Stack	** Closed.	DPAC	ASAP	
DENSE-034A	Internal Detectors for Capacitive Coupling Test	Patent	Original	4/19/2002	10/126,760			Internal Detectors for Capacitive Coupling Test	Closed.	PTO	None	
DENSE-035A	Socketed Stacking	Patent	Original					Socketed Stacking	** Closed	N/A	None	
DENSE-037A	3-D Memory Stacking Using Anisotropic Epoxy Interconnection	Patent	Original	4/5/2001	09/826,621	10/29/2002	6,472,735	3-D Memory Stacking Using Anisotropic Epoxy Interconnects	Issued. 3 1/2 year maintenance fees due 04/29/2006.	N/A	None	

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## EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required	Owner Assigned
DENSE-037G	Three-Dimensional Memory Stacking Using Anisotropic Epoxy Interconnections	Patent	Divisional	3/6/2002	10/092,073		3-D Memory Stacking Using Anisotropic Epoxy Interconnects		Closed.	PTO	None	DPAC 9/18/2003
DENSE-043A	Buried Device Slack	Patent	Original				Buried Device Slack	** Closed.		PTO	None	DPAC ASAP
DENSE-044A	Slice Interconnect Structure	Patent	Original	6/7/2002	10/161,329		Slice Interconnect Structure	Pending: Awaiting Receipt of Response to Restriction Requirement		PTO	None	
DENSE-044N	Slice Interconnect Structure	Patent	Provisional	6/15/2001	60/298,432		Slice Interconnect Structure	Utility Application Filed - See DENSE-044N		PTO	None	
DENSE-045A	I/O Interface Structure	Patent	Original	1/4/1900	10/160,857		I/O Interface Structure	** Closed.		PTO	None	
DENSE-045N	I/O Interface Structure	Patent	Provisional	6/15/2001	60/298,371		I/O Interface Structure	Utility Application Filed - See DENSE-045N		PTO	None	
DENSE-046A	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,173	6/3/2003	6,573,461	Retaining Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None	
DENSE-046G	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/3/2002	10/117,836			Retaining Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None	
DENSE-047A	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,190	6/3/2003	6,573,460	Post in Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None	
DENSE-047G	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/5/2002	10/117,245			Post in Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None	
DENSE-049A	Thermal Ring Used in 3-D Stacking	Patent	Original	11/6/2001	09/594,002			3-D Stacking Using Thermal Ring	** Closed.	PTO	None	
DENSE-051A	A Flex Tab for Use in Stacking Packaged Integrated Circuit Chips	Patent	Original	12/17/2001	10/024,389			Flex Tab Stacking	** Closed.	PTO	None	

## EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required	Owner Assigned
DENSE-052A	CSP Chip Stack with Flex Circuit	Patent	Original	12/14/2001	10/016,939			C-S Stack with Double Sided Flex and Formed Lead	** Closed.	PTO	None	
DENSE-053A	Folded Flex Circuit with z-axis Interconnect	Patent	Original					Folded Flex Circuit with z-axis Interconnect	Closed.	DPAC	None	
DENSE-055A	CS-STACK	Patent	Original					CS-STACK	Closed.	N/A	None	
DENSE-059A	Truck Transposer	Patent	Original	4/7/2003	10/408,317			Truck Transposer	** Closed.	PTO	None	
DENSE-060A	Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Patent	Original					Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Closed.	DPAC	None	
DENSE-061A	Direct Die Scale	Patent	Original					Direct Die Scale	Closed.	DPAC	None	
DENSE-062A	New Die Stack	Patent	Original					Near Die Stack	Closed.	DPAC	None	
DENSE-065A	T.S.O.P STACKING USING LASER/SPOT WELDING INTERCONNECT	Patent	Original					T.S.O.P STACKING USING LASER/SPOT WELDING INTERCONNECT	Closed (Combined with DENSE-067A)	N/A	None	
DENSE-066A	T.SOP STACKING USING UNDERLEAD INTERPOSER	Patent	Original	4/7/2003	10/408,697			TSOP STACKING USING UNDERLEAD INTERPOSER	** Closed.	PTO	None	
DENSE-067A	THIN SCALE OUTLINE PACKAGE STACK	Patent	Original	12/5/2002	10/310,368			THIN SCALE OUTLINE PACKAGE STACK	Response to OA due 6/24/04	PTO	6/24/04	
DENSE-067B	THIN SCALE OUTLINE PACKAGE STACK	Patent	Continuation-in-Part	7/14/03	10/620,157			THIN SCALE OUTLINE PACKAGE STACK	Awaiting Receipt of Response to Restriction Requirement	DPAC	None	
DENSE-067S	T.S.O.P. STACK PATENT SEARCH	Patent	Search					T.S.O.P. STACK PATENT SEARCH	Patent Search Opinion Letter to client 1/23/2002.	N/A	None	

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## EXHIBIT 1 - DPAC Assets

Updated: January 28, 2004

Case	True/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Action Assigned
DENSE-068A	T.SOP. POLYIMIDE FILM STRIP STACK	Patent	Original				T.S.O.P. POLYIMIDE FILM STRIP STACK	** Closed.		DPAC	None
DENSE-069A	TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	Patent	Original				TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	** Closed.		DPAC	None
DENSE-070A	STAR-STEP SIGNAL ROUTING	Patent	Original	4/21/2003	10/420,485		STAR-STEP SIGNAL ROUTING	Awaiting Receipt of Final Office Action		PTO	None
DENSE-071N	METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Patent	Provisional				METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Closed.		N/A	None
DENSE-072A	TSOP STACK ENHANCEMENTS	Patent	Original				TSOP STACK ENHANCEMENTS	Closed.		DPAC	None

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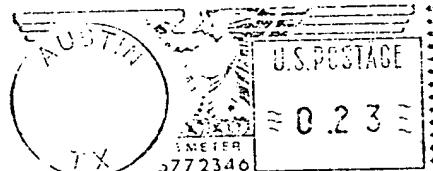
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Assignee: \_\_\_\_\_ Resp. Atty: \_\_\_\_\_  
Filing Date: \_\_\_\_\_ Date Mailed: \_\_\_\_\_  
Serial No.: 10/620,157 Date Due: \_\_\_\_\_  
Title: \_\_\_\_\_

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 Application PCT    Utility    Conversion    Amendment  
Prov \_\_\_\_\_ Div \_\_\_\_\_ Cont \_\_\_\_\_ CPA \_\_\_\_\_ Reissue \_\_\_\_\_  
Spec \_\_\_\_\_ pages; Claims \_\_\_\_\_ pages       Extension of Time Request \_\_\_\_\_ mos.  
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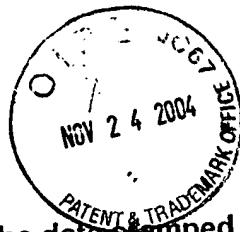
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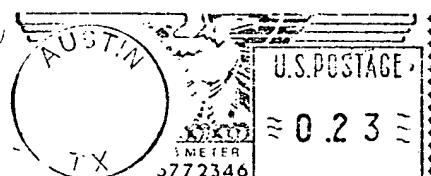
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Serial No.: 10/620,157 Date Due: \_\_\_\_\_  
Title: \_\_\_\_\_

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 Application PCT  Utility  Conversion \_\_\_\_\_  
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Spec    pages; Claims    pages  
Drawings    pages; Abstract    pages  
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